

# RF4G060AT

## Pch -40V -6A Power MOSFET

V <sub>DSS</sub>	-40V
R <sub>DS(on)</sub> (Max.)	40mΩ
I <sub>D</sub>	±6.0A
$P_D$	2.0W

### Features

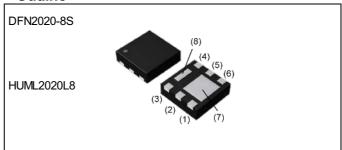
- 1) Low on resistance
- 2) High power small mold package (HUML2020L8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

## Application

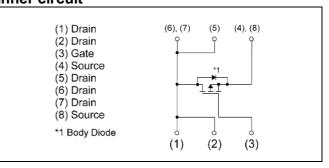
Switching

Load switch

### Outline



## ●Inner circuit



Packaging specifications

•		
	Packing	Embossed Tape
	Reel size (mm)	180
Type	Tape width (mm)	8
	Quantity (pcs)	3000
	Taping code	TCR
	Marking	KS

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

	0 1 1		
Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	-40	V
Continuous drain current	I <sub>D</sub>	±6.0	А
Pulsed drain current	I <sub>DP</sub> *1	±24	Α
Gate - Source voltage	$V_{GSS}$	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *2	-6.0	Α
Avalanche energy, single pulse	E <sub>AS</sub> *2	2.8	mJ
Power dissipation	P <sub>D</sub> *3	2.0	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Cumbal	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R <sub>thJA</sub> *3	-	-	62.5	°C/W

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah al	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = -1mA$	-40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	-22	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V	-	-	-1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	ı	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -1mA$	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = -1mA referenced to 25°C	-	3.7	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = -10V, I <sub>D</sub> = -6.0A	-	32	40	O	
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -6.0A	-	40	51	mΩ	
Gate resistance	$R_G$	f=1MHz, open drain	-	16	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = -5.0V, I <sub>D</sub> = -6.0A	5.5	-	-	S	

<sup>\*1</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*2</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = -20V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>i</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*3</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*4</sup> Pulsed

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	880	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -20V	-	130	1	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	80	1	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -20V, V_{GS} = -10V$	1	9.5	ı	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = -3A	1	18.0	ı	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 6.6\Omega$	-	83.0	-	ns
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	45.0	-	

## • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			1.1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *4		V <sub>GS</sub> = -10V	-	17.2	-	
Total gate charge	$Q_g^{*4}$	V <sub>DD</sub> ≃ <b>-</b> 20V		-	8.5	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = -6A	V <sub>GS</sub> = -4.5V	-	2.7	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4			-	3.4	-	

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	-1.67	Α
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25°C	-	-	-24	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_S = -1.67A$	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -6A, V <sub>GS</sub> =0V	-	26	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	24	-	nC

Fig.1 Power Dissipation Derating Curve

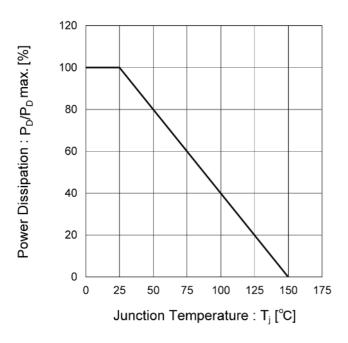
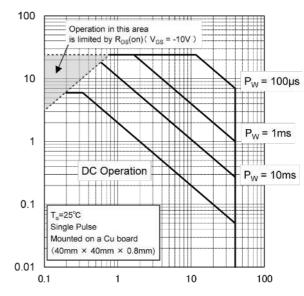


Fig.2 Maximum Safe Operating Area



Drain Current: -I<sub>D</sub> [A]

Drain - Source Voltage : -VDS [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

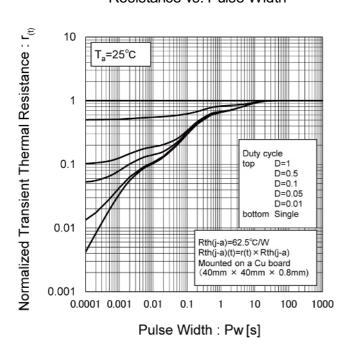


Fig.4 Single Pulse Maximum Power Dissipation

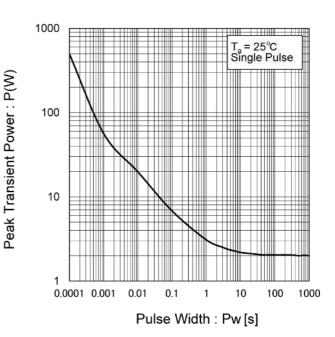


Fig.5 Typical Output Characteristics(I)

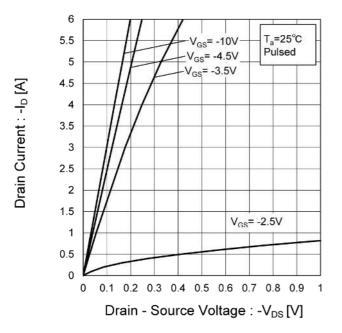


Fig.6 Typical Output Characteristics(II)

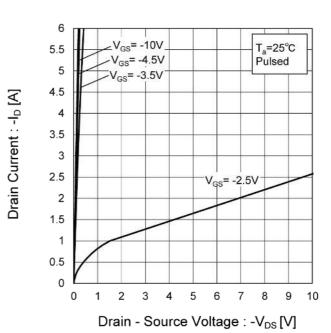


Fig.7 Breakdown Voltage vs.
Junction Temperature

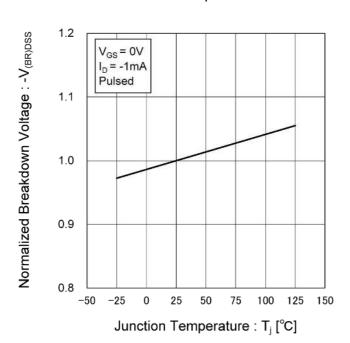


Fig.8 Typical Transfer Characteristics

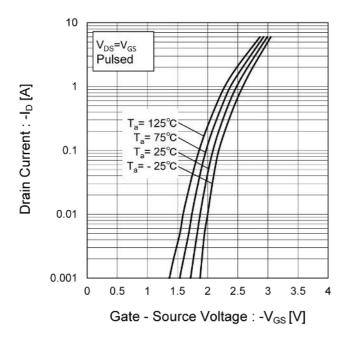


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

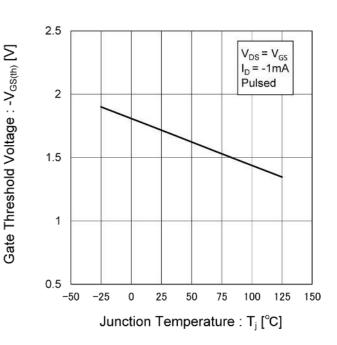
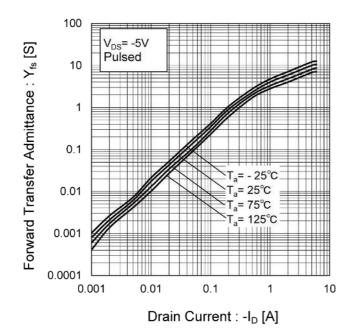


Fig.10 Forward Transfer Admittance vs.
Drain Current



6/11

Fig.11 Drain Current Derating Curve

120 100 **Drain Current Dissipation** 80 : I<sub>D</sub>/I<sub>D</sub>max. [%] 60 40 20 0 -25 25 50 75 100 125 150 Junction Temperature :  $T_j$  [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

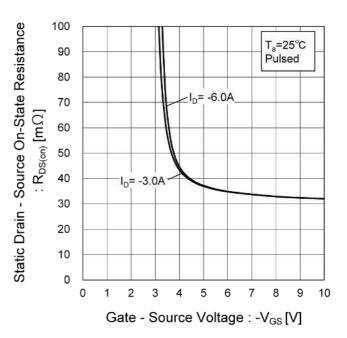


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

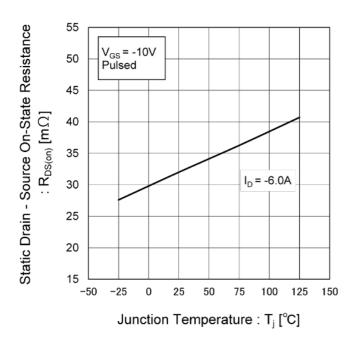


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

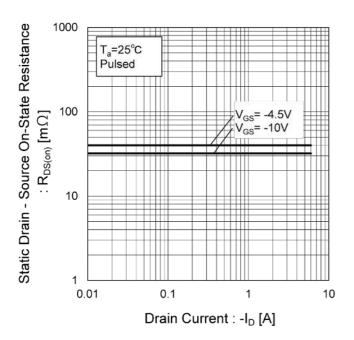


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

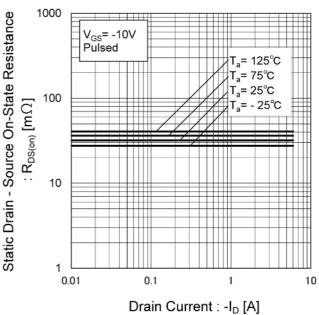


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

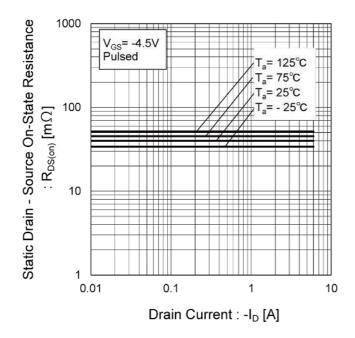


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

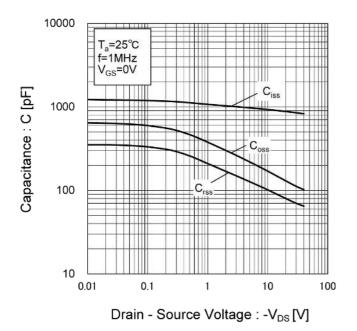


Fig.18 Switching Characteristics

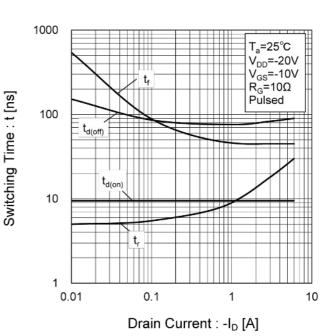


Fig.19 Typical Gate Charge

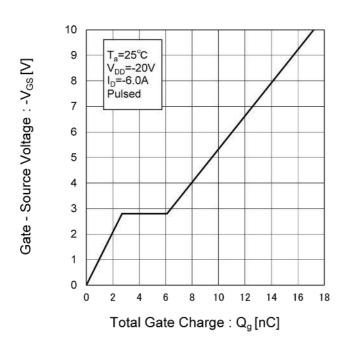
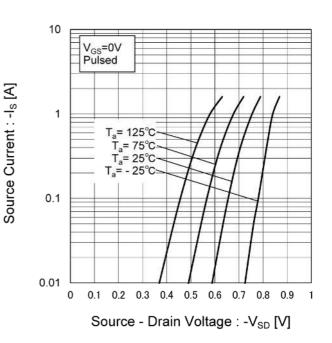


Fig.20 Source Current vs.

Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

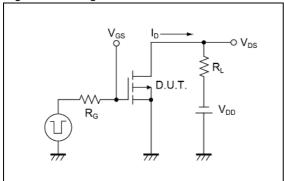


Fig.2-1 Gate Charge Measurement Circuit

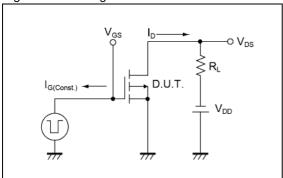


Fig.3-1 Avalanche Measurement Circuit

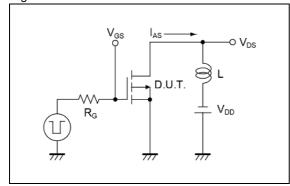


Fig.1-2 Switching Waveforms

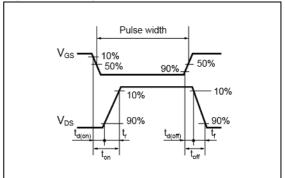


Fig.2-2 Gate Charge Waveform

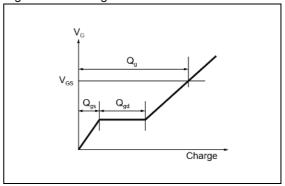
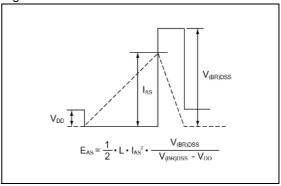
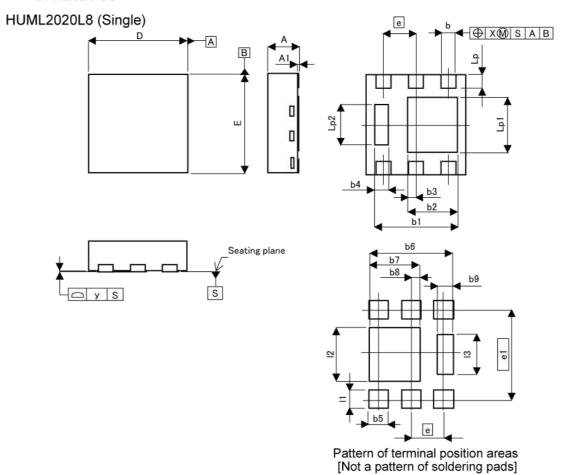


Fig.3-2 Avalanche Waveform



## Dimensions

## DFN2020-8S



DIM I	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.55	0.65	0.022	0.026
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
b1	1.55	1.75	0.061	0.069
b2	0.95	1.05	0.037	0.041
b3	0.175		0.0	007
b4	0.	25	0.0	)10
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
е	0.60	0.70	0.024	0.028
Lp	0.225	0.325	0.009	0.013
Lp1	1.00	1.20	0.039	0.047
Lp2	0.	80	0.0	31
x	-	0.10		0.004
У		0.10	3.53	0.004

DIM	MILIM	MILIMETERS		HES	
DIIVI	MIN	MAX	MIN	MAX	
b5	3-67	0.45	3₩3	0.018	
b6		1.75	540	0.069	
b7	-	1.05	- 6	0.041	
b8	0.175		0.	007	
b9	. <b>.</b>	0.30	3.00	0.012	
e1	1.725		0.	068	
11		0.425	171	0.017	
12	3-67	1.15	370	0.045	
13	(4)	0.85	34	0.033	

Dimension in mm/inches



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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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